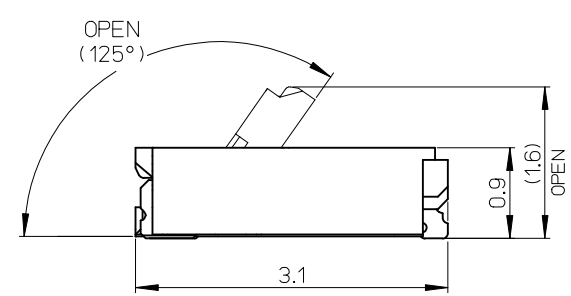


注記
NOTES:
1.材質
MATERIAL
ハウジング:LCP(液晶ポリマー)、ガラス充填、UL94V-0
HOUSING:LCP(LIQUID CRYSTAL POLYMER),
GLASS FILLED,UL94V-0
アクチュエータ:ナイロン、ガラス充填、UL94V-0
ACTUATOR:NYLON(POLYAMIDE),
GLASS FILLED,UL94V-0
ターミナル:銅合金(t=0.15)
TERMINAL:COPPER ALLOY(t=0.15)
金具:銅合金(t=0.15)
NAIL:COPPER ALLOY(t=0.15)

2.めっき仕様
PLATING
ターミナル
TERMINAL
部分金めっき
SEPARATED GOLD PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
金具
NAIL
銅めっき
TIN PLATING
下地ニッケルめっき
UNDER PLATING:NICKEL PLATING
3.平坦度は、0.1ミリ以下とする。
TAILS COPLANARITY TO BE 0.1 MAXIMUM.
4.ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

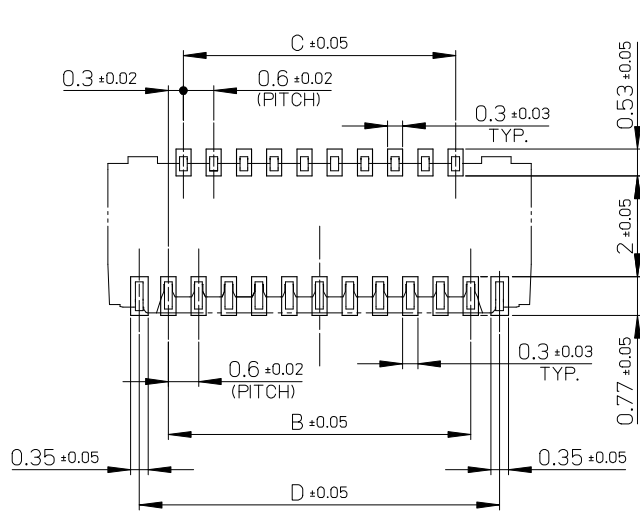


0.10	16.15	14.4	15	17.4	501628-5191	51
0.089	14.35	12.6	13.2	15.6	501628-4591	45
0.078	12.55	10.8	11.4	13.8	501628-3991	39
0.075	11.95	10.2	10.8	13.2	501628-3791	37
0.071	11.35	9.6	10.2	12.6	501628-3591	35
0.067	10.75	9.0	9.6	12.0	501628-3391	33
0.064	10.15	8.4	9	11.4	501628-3191	31
0.056	8.95	7.2	7.8	10.2	501628-2791	27
0.046	7.15	5.4	6	8.4	501628-2191	21
0.028	4.15	2.4	3	5.4	501628-1191	11
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER No.	極数 CIRCUITS

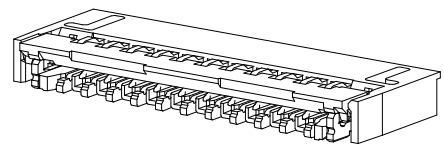
CONNECTOR SERIES No. 501628-**11

REVISED EC NO: J2010-0068 DRW:KUSATO 2009/07/30 CHKD:SHIMOMIYAMA 2009/07/31 APPR:KMORIKAWA 2009/07/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 40:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HSHIMOMIYAMA	DATE 2005/03/25	TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER	
	10 OVER 30 UNDER	±0.25	CHECKED BY HHIRATA	DATE 2005/03/25	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY MSASAO	DATE 2005/03/25	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501628-001
REV	DESCRIPTION	ANGULAR ±1°	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

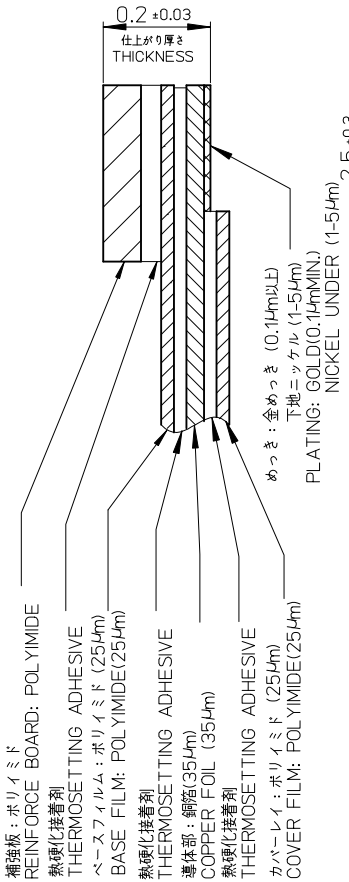
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS



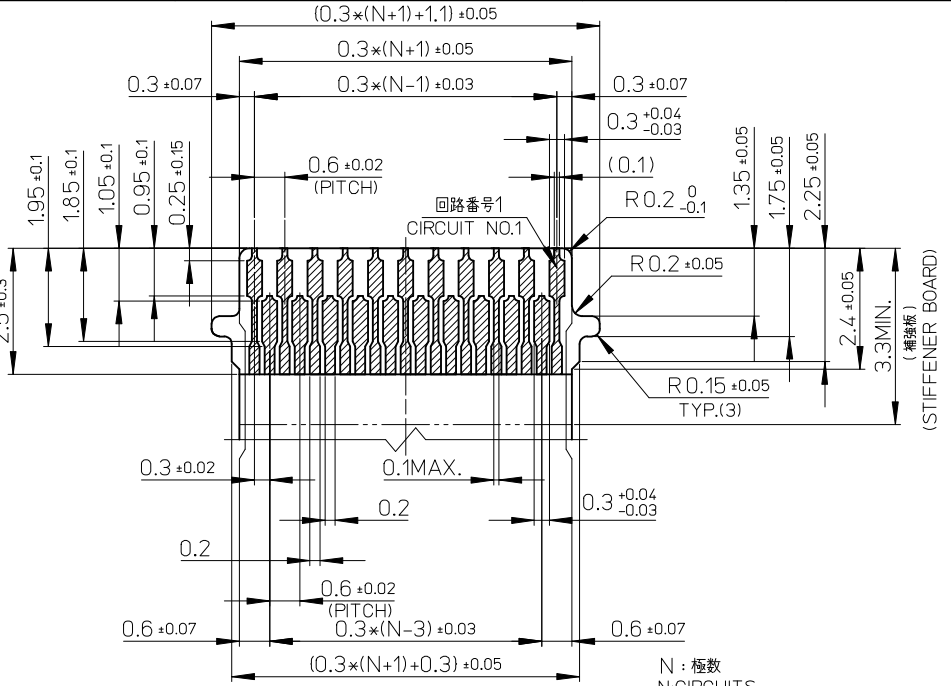
推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT
(SCALE 5:1)



ISO VIEW (参考)



FPC構成推奨仕様
STRUCTURE OF FPC



適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

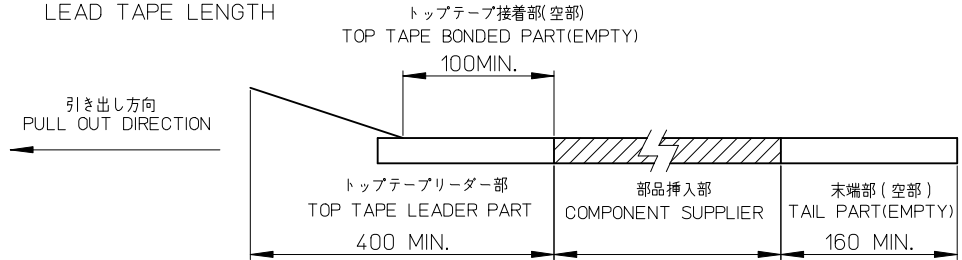
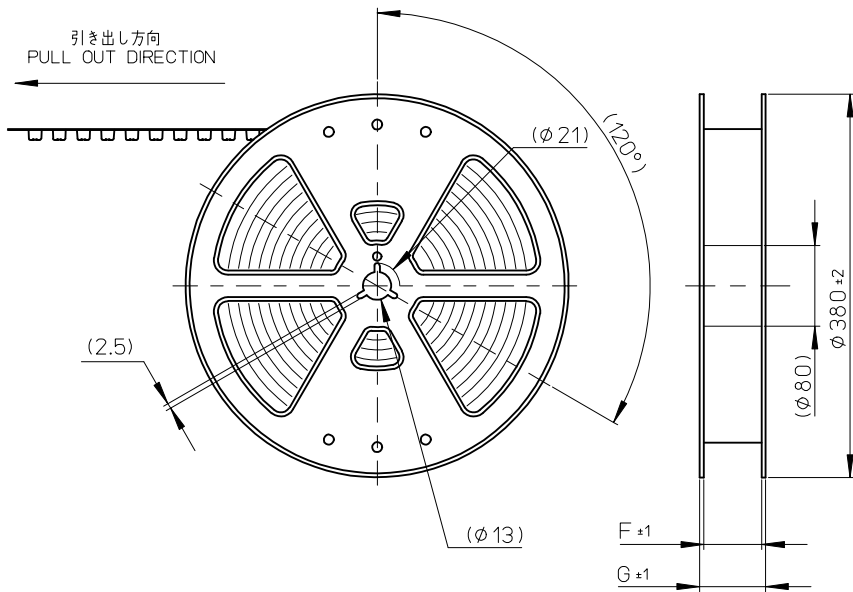
FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

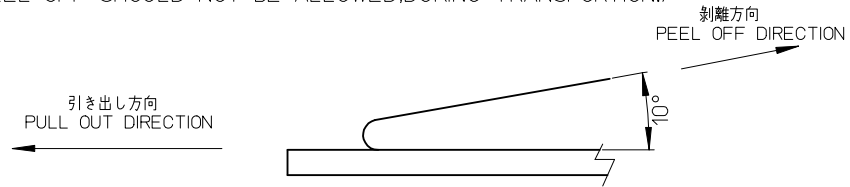
REVISED EC NO: J2010-0068 DRWN:KUSATO 2009/07/30 CHKD:HSHIROYAMA 2009/07/31 APPR:KMORIKAWA 2009/07/31	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 40:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY HSHIROYAMA	DATE 2005/03/25	TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER			
		10 OVER 30 UNDER	± 0.25	CHECKED BY HHIRATA	DATE 2005/03/25	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2005/03/25	DOCUMENT NO. SD-501628-001			
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

注記)
NOTES

1. 製品番号501628-***11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 501628-***11 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量: 3000個/リール
NUMBER OF CONNECTORS : 3000 PCS/REEL
3. リードテープ長さ
LEAD TAPE LENGTH



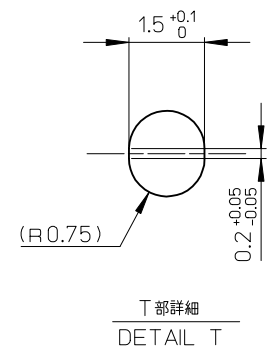
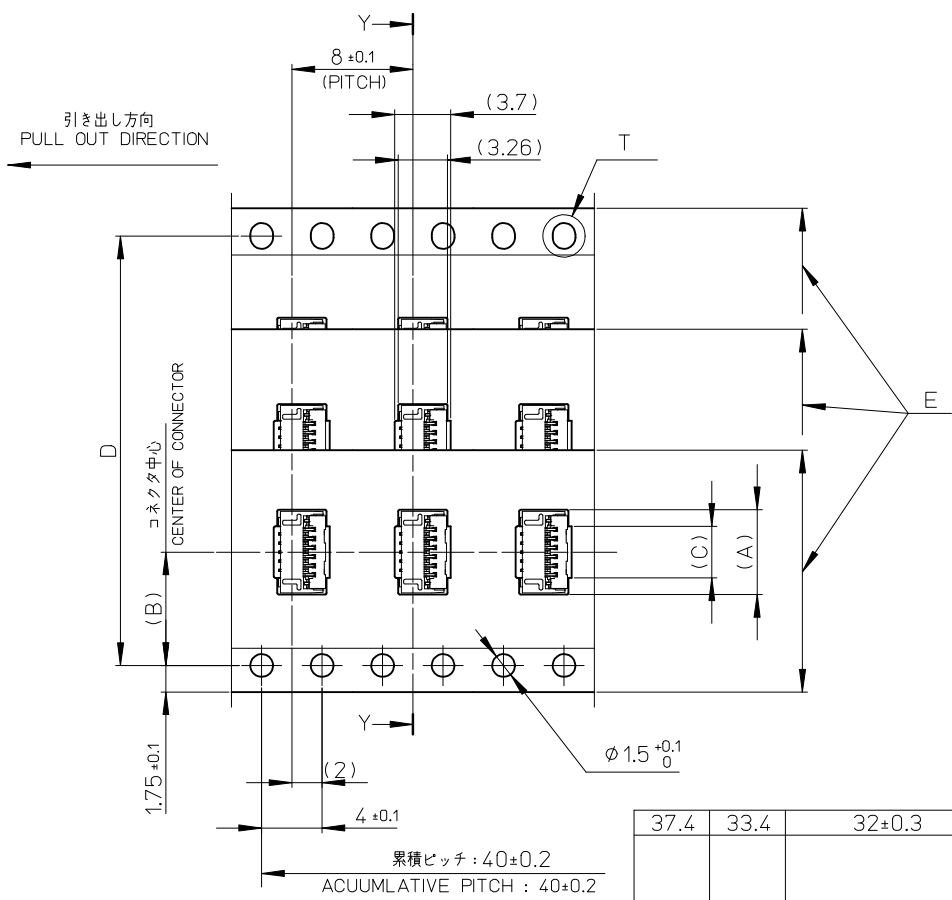
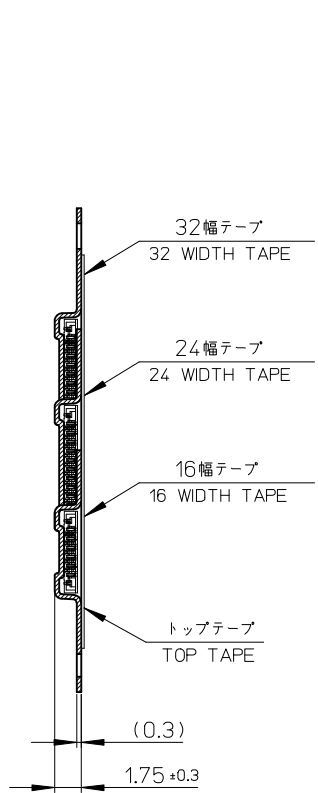
4. トップテープの剥離強度 (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
0.1-1.3N (10-130gf)
尚、本規格値は出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しないこと)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.)



5. 材料
MATERIAL
キャリアテープ: ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ: PET、PE、PEF
TOP TAPE : PET, PE, PEF
リール: ポリスチレン
REEL: POLYSTYRENE

6. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

REVISED EC NO: J2010-0068 DRWN: KUSATO 2009/07/30 CH'KD: HSHIMYOYAMA 2009/07/31 APPR: KMORIKAWA 2009/07/31	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY HSHIMYOYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628-***11) TAPING PACKAGE NICKEL BARRIER		
	10 OVER 30 UNDER	± ---	CHECKED BY HHIRATA	DATE 2005/08/22	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501628-003	SHEET NO. 1 OF 2
REV	DESCRIPTION	ANGULAR ± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



37.4	33.4	32 ± 0.3	28.4	15.4	14.2	17.6	501628-5191	51	
29.4	25.4	24 ± 0.3	---	13.6	11.5	15.8	501628-4591	45	
				11.8		14	501628-3991	39	
				11.2		13.4	501628-3791	37	
				10.6		12.8	501628-3591	35	
				10.0		12.2	501628-3391	33	
				9.4		11.6	501628-3191	31	
21.4	17.4	16 ± 0.3	---	8.2	7.5	10.4	501628-2791	27	
				6.4		8.6	501628-2191	21	
				3.4		5.6	501628-1191	11	
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH		D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2010-0068 DRW: KUSATO 2009/07/30 CHK: HSHIMUYAMA 2009/07/31 APP: KMORIKAWA 2009/07/31	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY HSHIMUYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER				
		10 OVER 30 UNDER	± ---	CHECKED BY HHRATA	DATE 2005/08/22	MOLEX INCORPORATED				
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501628-003	SHEET NO. 2 OF 2	
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						